

**IN THE CLAIMS:****Please enter the following claims:****Please cancel Claims 11-19 and 21-22.**

23. (currently amended) A slurry for performing chemical mechanical polishing (CMP) of oxides on a substrate, comprising:

ceria particles having a first concentration; and

silica particles having a second concentration, wherein

the concentration of ceria in the slurry is approximately 1.0 – 5.0 wt%;

the concentration of silica in the slurry is approximately 0.1 – 5.0 wt%;

wherein a ratio of ceria concentration to silica concentration (ceria:silica) is from approximately 10:1 to nearly 1:1 by weight;

the ceria particles have a particle size of 150-250nm; and

the silica particles have a particle size ~~ef~~ greater than 100nm;

wherein the silica particles comprise fumed silica; and

wherein the slurry has a pH in the range of from 7-12.

24. (previously added) The slurry of claim 23, wherein the ratio of ceria:silica is selected from the group consisting of from 10:1 to 7:1; from 10:1 to 4:1; from 10:1 to 1.1:1; approximately 10:1; approximately 7:1; approximately 4:1; greater than 4:1; and greater than 7:1.

25. (previously added) The slurry of claim 23, wherein the ceria particles have a first particle size and the silica particles have a second particle size; and a ratio of first particle size to second particle size (ceria:silica) is selected from the group consisting of approximately 1:1; approximately 1.5:1; approximately 2:1; and approximately 2.5:1.

26. (previously added) The slurry of claim 23, wherein the ceria particles have a particle size of 180:220nm; and

the silica particles have a particle size of 130:190nm.

27. (previously added) The slurry of claim 23, wherein the slurry has a pH of approximately 9.0.

28. (previously added) The slurry of claim 23, wherein the slurry has a pH in the range of from 8.5 to 9.5.